

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chang, et al.

Serial No.: 10/634,662

Filed:

August 4, 2003

Confirmation No.: 6355

For:

Ruthenium Layer

Formation for Copper Film

Deposition

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Group Art Unit: 1762

Examiner:

Unknown

MAIL STOP NON-FEE AMENDMENT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 CERTIFICATE OF MAILING 37 CFR 1.8

I hereby certify that this correspondence is being deposited on March 24, 2004 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

3/24/04

Signature

Dear Sir:

PRELIMINARY AMENDMENT

Prior to examination, please amend the above-identified application as shown in the following pages. Amendments to the Specification begin on page 2. Remarks begin on page 3.